



100V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	Rds(on) Max	I _D Tc = +25°C
100V	8.9mΩ @ V _{GS} = 10V	88A

Description

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize R_{DS(ON)} yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

Applications

- Motor controls
- DC-DC converters
- Power managements

Features

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- <1.1mm Package Profile Ideal for Thin Applications (PowerDI[®])
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An automotive-compliant part is available under separate datasheet (<u>DMTH10H009SPSQ</u>)

Mechanical Data

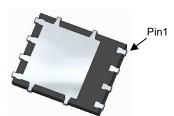
- Package: PowerDI5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208³
- Weight: 0.097 grams (Approximate)

Site 1:

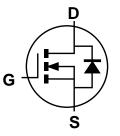




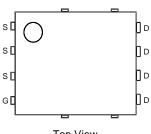
Top View



Bottom View



Internal Schematic



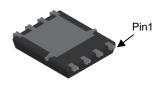
Top View Pin Configuration

Site 2:

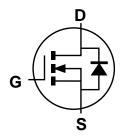
PowerDI5060-8/SWP (Type UX)



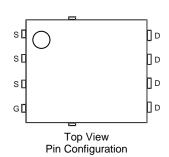
Top View



Bottom View



Internal Schematic



Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



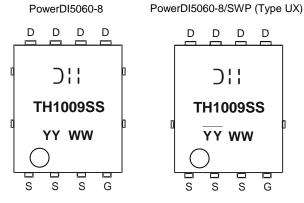
Ordering Information (Note 4)

Part Number	Paakaga	Packing		
Fait Number	Package	Qty.	Carrier	
DMTH10H009SPS-13	PowerDI5060-8	2,500	Tape & Reel	
DMTH10H009SPS-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel	

Note:

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



) | | = Manufacturer's Marking TH1009SS = Product Type Marking Code YYWW or YYWW = Date Code Marking YY or \overline{YY} = Last Two Digits of Year (ex: 23 = 2023) WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	100	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current V _{GS} = 10V (Note 6)	Steady State	$T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$	lD	16 11	Α
Continuous Drain Current V _{GS} = 10V (Note 7)	I _D	88 62	Α		
Pulsed Drain Current (10µs Pulse, Tc = +25°C, Package Li	I _{DM}	350	Α		
Maximum Continuous Body Diode Forward Current			Is	83	Α
Pulsed Body Diode Current (10μs Pulse, T _C = +25°C, Package Limited)			Ism	350	Α
Avalanche Current (Note 8), L = 3mH			I _{AS}	11	Α
Avalanche Energy (Note 8), L = 3mH			E _{AS}	181.5	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	PD	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	94	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	PD	3.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	47	°C/W
Total Power Dissipation (Note 7)	T _C = +25°C	PD	100	W
Thermal Resistance, Junction to Case (Note 7)		R _θ JC	1.5	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.



Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

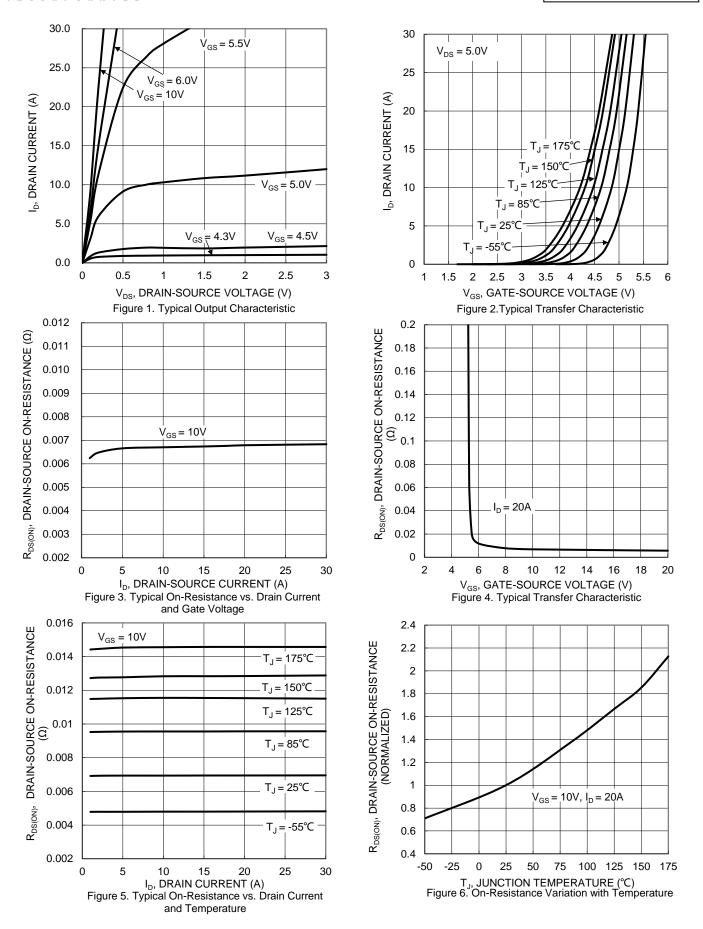
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BVDSS	100	_	_	٧	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	$V_{DS} = 80V$, $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	Vgs(th)	2	_	4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	RDS(ON)	_	6.7	8.9	mΩ	$V_{GS} = 10V, I_{D} = 20A$	
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 13A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	_	2085	_		V _{DS} = 50V, V _{GS} = 0V f = 1MHz	
Output Capacitance	Coss	_	609	_	pF		
Reverse Transfer Capacitance	Crss	_	13	_			
Gate Resistance	R_g	_	1.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	30	_		\/ 50\/ I- 42A	
Gate-Source Charge	Qgs	_	9.5	_	nC	$V_{DD} = 50V, I_{D} = 13A,$ $V_{GS} = 10V$	
Gate-Drain Charge	Q_{gd}	_	7.3	_			
Turn-On Delay Time	tD(ON)	_	9.7	_			
Turn-On Rise Time	t _R	_	13.7	_	ns	$\begin{split} V_{DD} &= 50 \text{V}, \ V_{GS} = 10 \text{V}, \\ I_D &= 13 \text{A}, \ R_g = 6 \Omega \end{split}$	
Turn-Off Delay Time	tD(OFF)	_	25.1	_			
Turn-Off Fall Time	tF	_	17.3	_			
Reverse Recovery Time	trr	_	45	_	ns	I 424 di/dt 4004/ve	
Reverse Recovery Charge	Qrr	_	68	_	nC	I _F = 13A, di/dt = 100A/μs	

Notes:

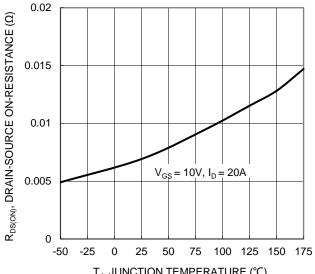
^{9.} Short duration pulse test used to minimize self-heating effect.10. Guaranteed by design. Not subject to product testing.











T_J, JUNCTION TEMPERATURE (°C) Figure 7. On-Resistance Variation with Temperature

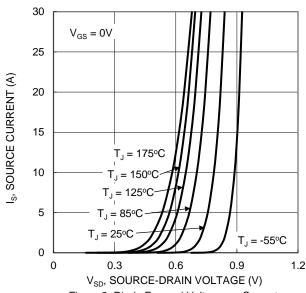
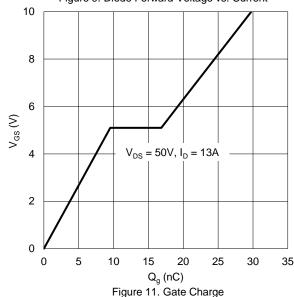


Figure 9. Diode Forward Voltage vs. Current



4 $V_{GS(TH)}, GATE THRESHOLD VOLTAGE (V)$ 3.5 $I_D = 1mA$ 3 2.5 2 $I_{D} = 250 \mu A$ 1.5 1 0.5 -50 -25 25 50 75 100 125 150 175

T_J, JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature

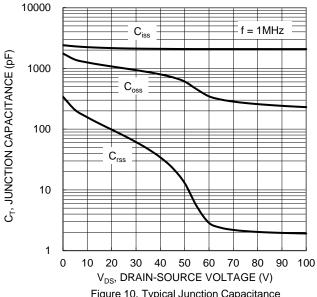
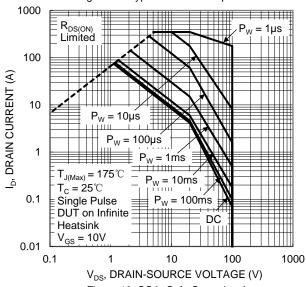


Figure 10. Typical Junction Capacitance





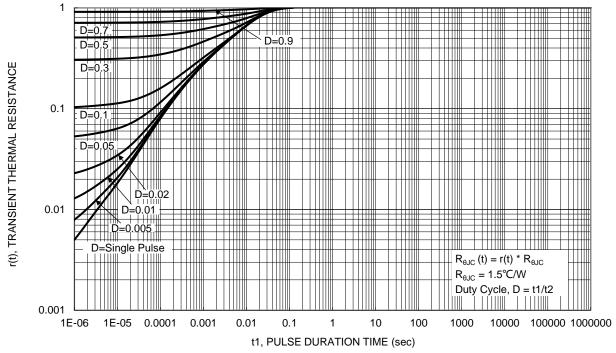


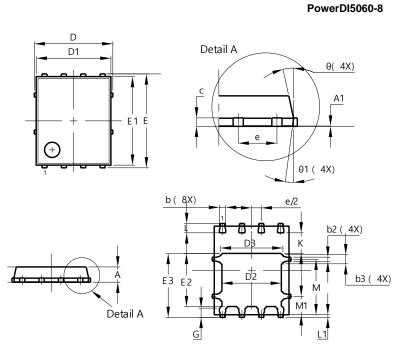
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

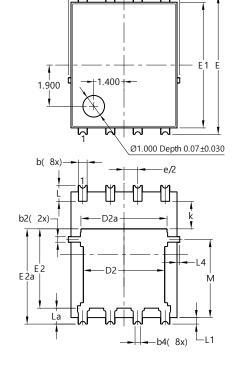
Site 1:



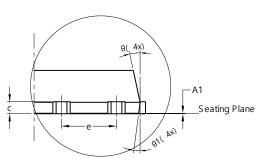
PowerDI5060-8				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0.00	0.05	-	
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D	,	5.15 BSC		
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
Е	(6.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е		1.27 BSC	,	
G	0.51	0.71	0.61	
K	0.51	-	-	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
M	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
Θ	10°	12°	11°	
Θ1	6°	8°	7°	
All Dimensions in mm				

Site 2:

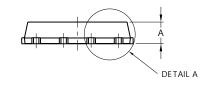
PowerDI5060-8/SWP (Type UX)



D1



DETAIL A



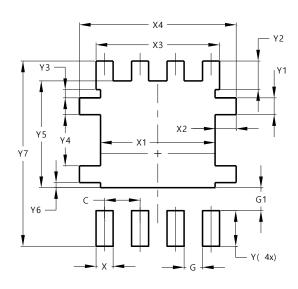
PowerDI5060-8/SWP				
(Type UX)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4	C).25REF	-	
С	0.230	0.330	0.277	
D	5	.15 BS0		
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	.40 BS0	\sim	
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е	1	.27BSC)	
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L1a	0.050REF			
L4	0.025	0.225	0.125	
M	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				



Suggested Pad Layout

Site 1:

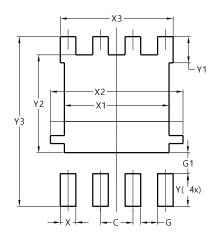
PowerDI5060-8



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
Х	0.610
X1	4.100
X2	0.755
Х3	4.420
X4	5.610
Υ	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y 7	6.610

Site 2:

PowerDI5060-8/SWP (Type UX)



Dimensions	Value
Dillielisions	(in mm)
С	1.270
G	0.660
G1	0.820
Χ	0.610
X1	4.100
X2	5.190
Х3	4.420
Υ	1.270
Y1	1.020
Y2	3.810
Y3	6.610



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